

Layout Design Automation: From Academia to Industry and Back

Jens Lienig



Prof. Dr.-Ing. Dr. h.c. Dieter A. Mlynski
1932 - 2024



Atlantic Ocean

Pacific Ocean

Indian Ocean

Starting in Academia: My First Paper (EDAC, 1992)

Routing Algorithms for Multi-Chip Modules

Jens Lienig, K. Thulasiraman, M. N. S. Swamy

Department of Electrical and Computer Engineering
Concordia University
1455 de Maisonneuve Blvd. West
Montreal, Quebec H3G 1M8, Canada

Abstract

We present routing algorithms for multi-chip modules. Two routing strategies, a channel routing and a grid-based routing, are discussed. The channel routing enables the designer to examine an effective routing during the placement phase. The grid-based routing calculates the net ordering with a new cost function and includes an effective rip-up and reroute procedure. The paper concludes with the presentation of some routing results.

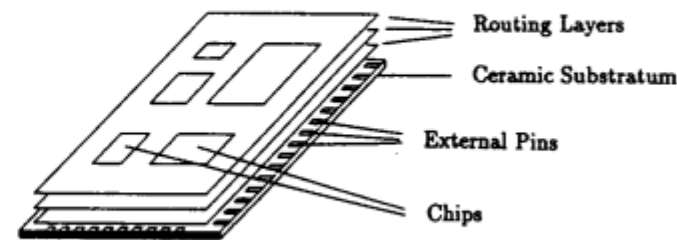


Figure 1: A multi-chip module

Starting in Academia: Moving into Evolutionary Algorithms

A New Genetic Algorithm for the Channel Routing Problem

Jens Lienig* and K. Thulasiraman

Department of Electrical and Computer Engineering
Concordia University

A new genetic algorithm for channel routing in VLSI circuits is presented. The algorithm is based on a parallel distributed network of processors. It minimizes both physical cost (vias) and crosstalk (delay). The results show that our parallel algorithm yields results that are better or as good as the best published results.

1 Introduction

Channel routing is a fundamental problem in VLSI design. It involves finding a path for each net in a circuit, subject to various constraints such as routing area, crosstalk, and delay. The channel routing problem is NP-complete, and therefore, there is no known polynomial-time algorithm to solve it. In this paper, we present a new genetic algorithm for channel routing. The algorithm is based on a parallel distributed network of processors. It minimizes both physical cost (vias) and crosstalk (delay). The results show that our parallel algorithm yields results that are better or as good as the best published results.

New approach

A PARALLEL GENETIC ALGORITHM FOR CHANNEL ROUTING PROBLEMS

Jens Lienig

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Email: jens@virginia.edu

IEEE TRANSACTIONS ON EVOLUTIONARY COMPUTATION

This paper presents a new genetic algorithm for channel routing in VLSI circuits. The algorithm is based on a parallel distributed network of processors. It minimizes both physical cost (vias) and crosstalk (delay). The results show that our parallel algorithm yields results that are better or as good as the best published results.

1. INTRODUCTION

C6.3 Parallel Genetic Algorithms Based on Punctuated Equilibria

W N Martin, J Lienig and J P Cohoon

Department of Computer Science, University of Virginia

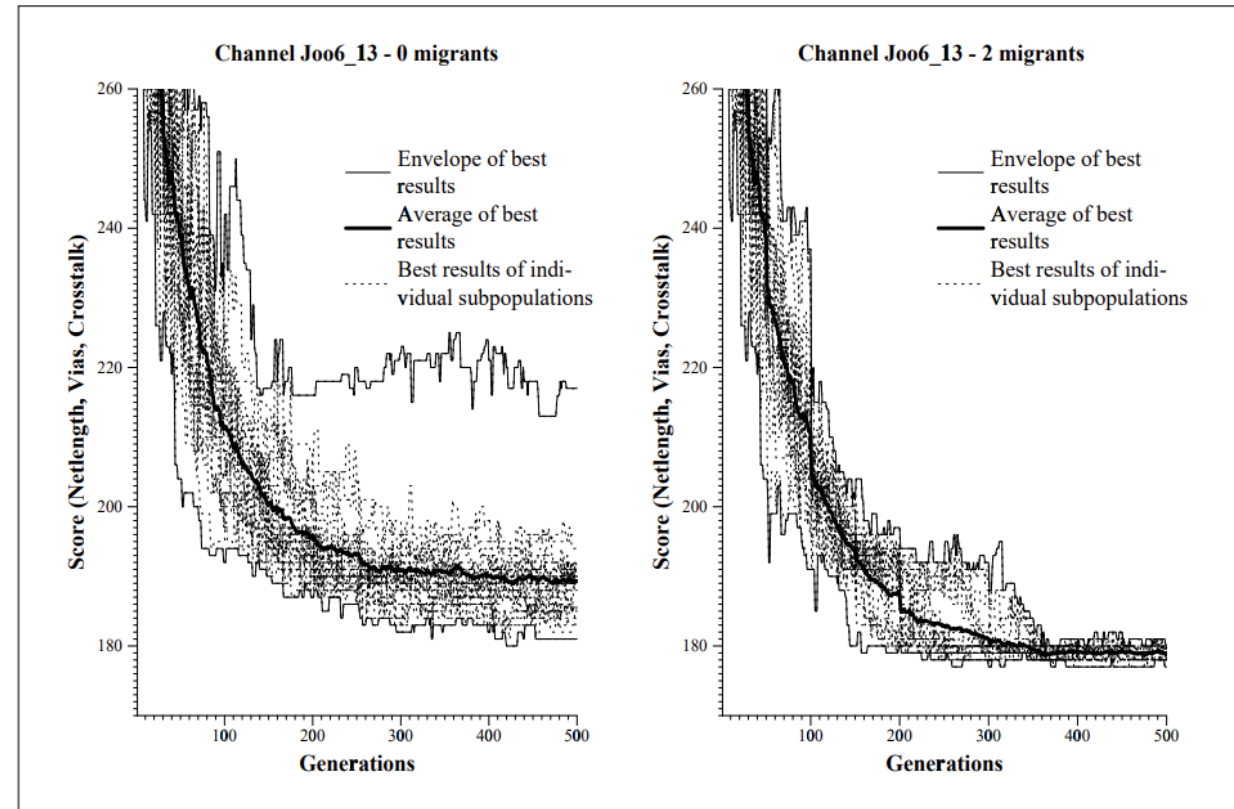
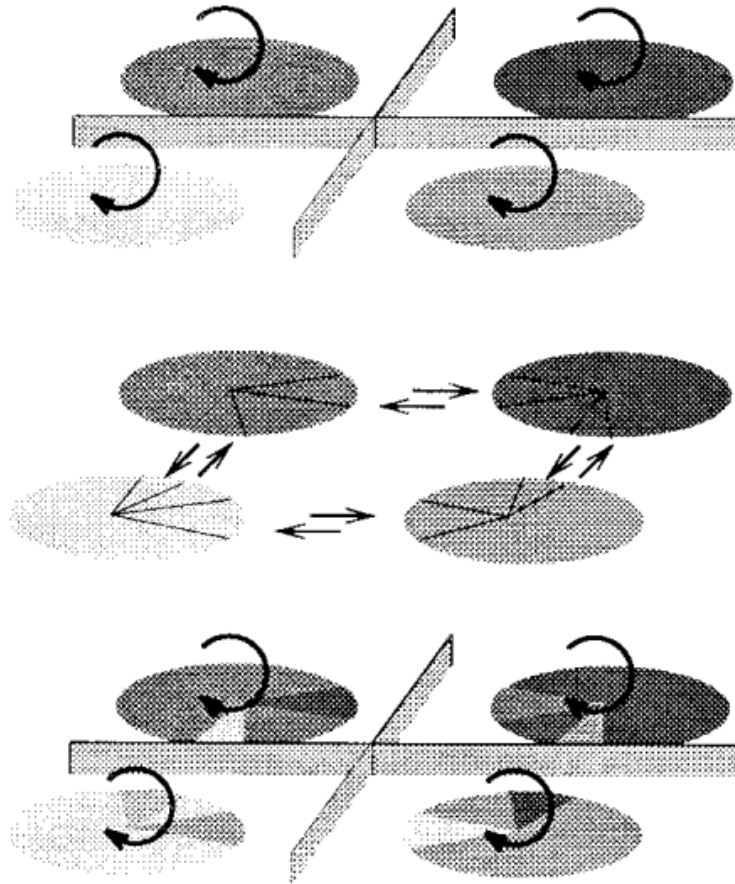
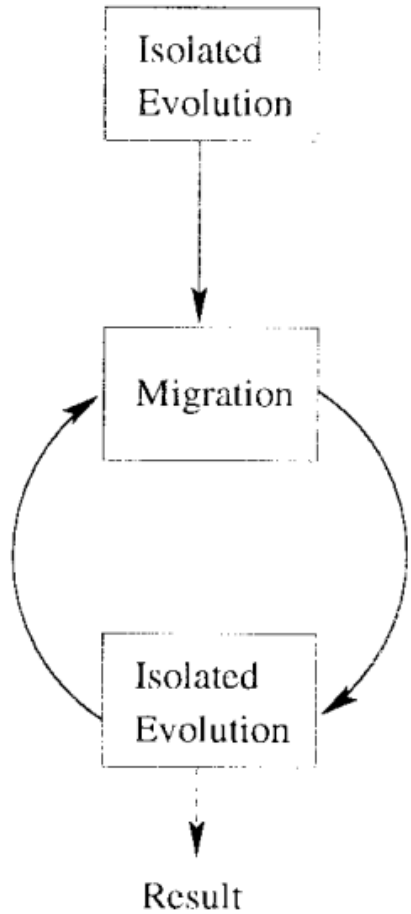
Abstract

The island model genetic algorithm shows promise as a superior formulation based on considerations from theories of natural evolution and from the efficiencies of coarse-grained parallel computer architectures. The theory of "punctuated equilibria" calls for the population to be partitioned into several distinct subpopulations. These subpopulations have extensive periods of isolated evolution, i.e., computation, occasionally interspersed with migration, i.e., communication. It is precisely for this sort of process with its alternating phases of extended computation and limited communication that message-passing multi-processors (implementing coarse-grained parallelism) are best suited. We validate this promise of the island model and illustrate the effects of varying configuration attributes through experiments with a difficult VLSI design problem.

A Parallel Genetic Algorithm for Performance-Driven VLSI Routing

Jens Lienig, *Member, IEEE*

Parallel Genetic Algorithms Based on Punctuated Equilibria

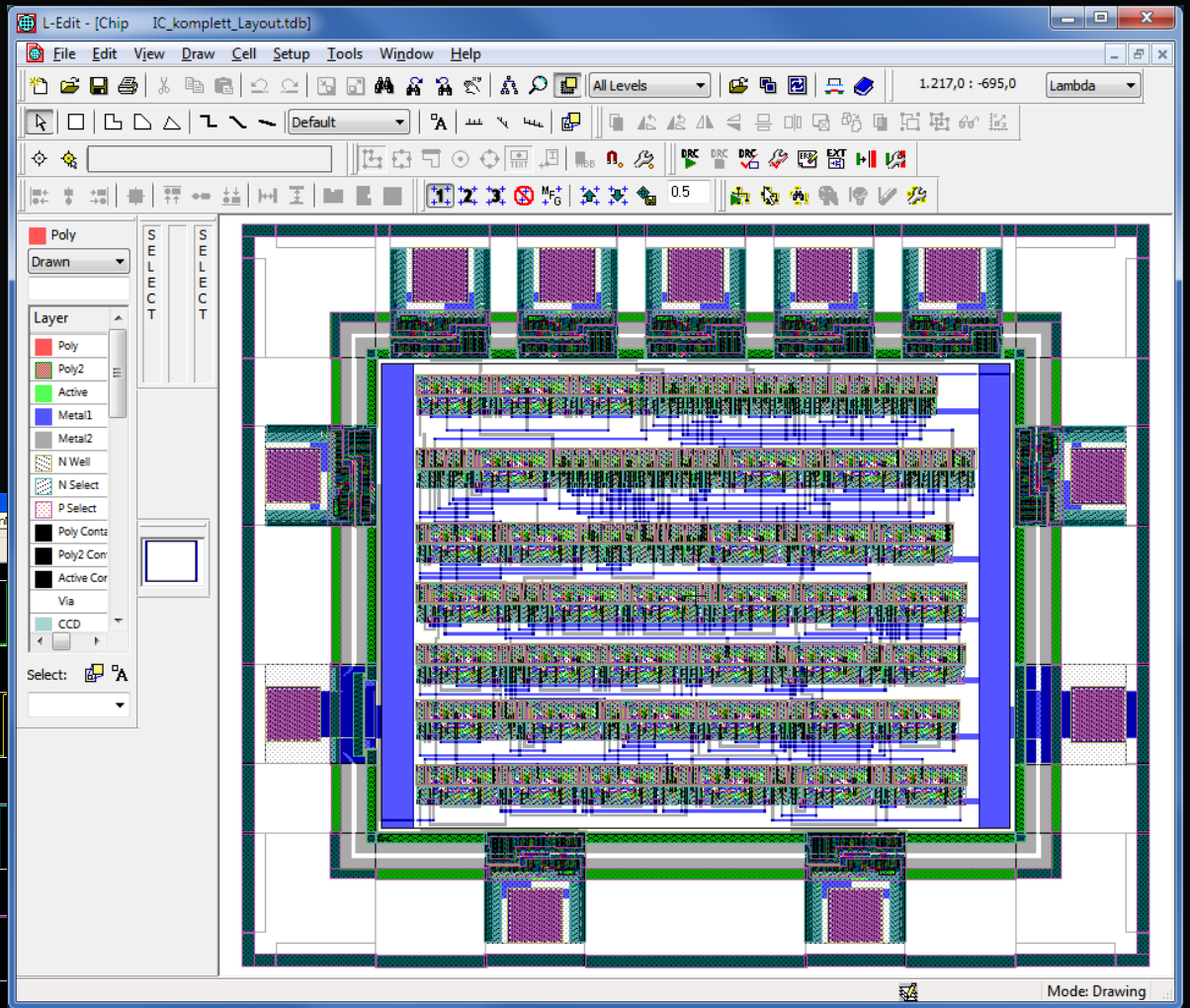
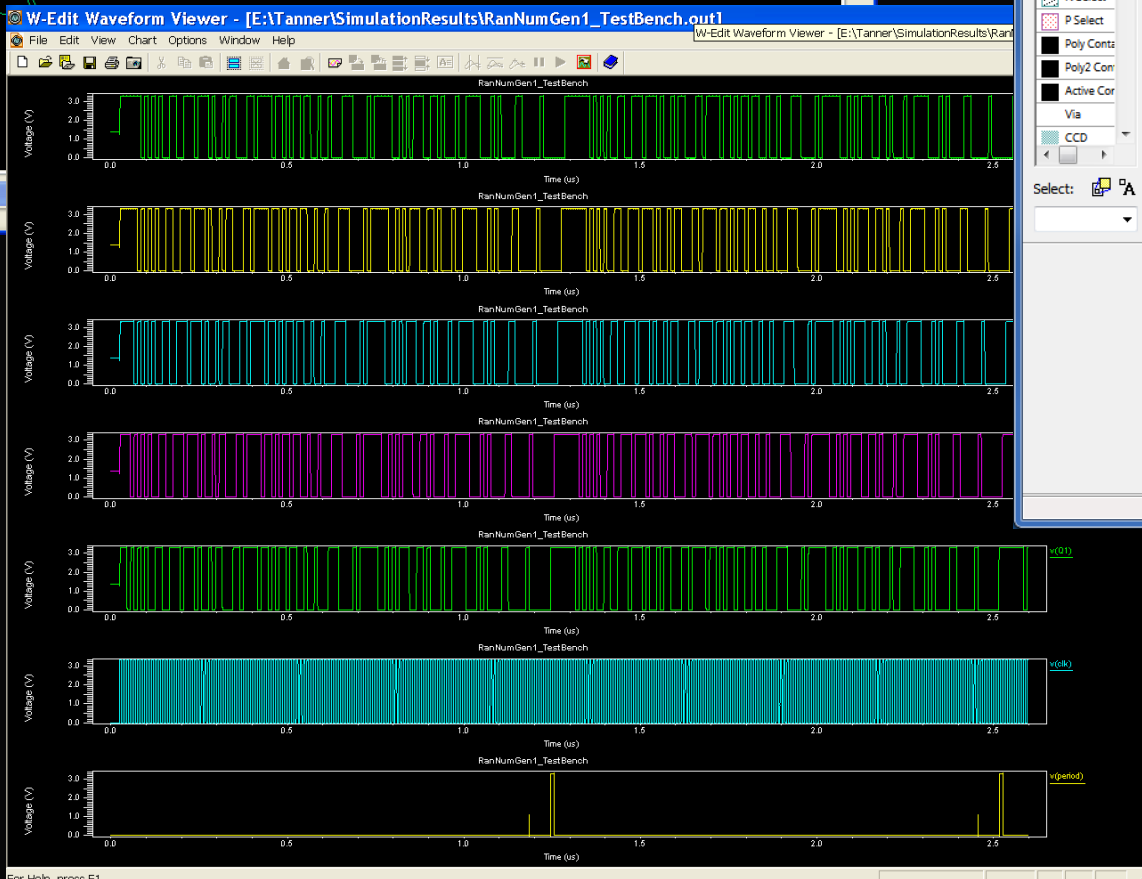
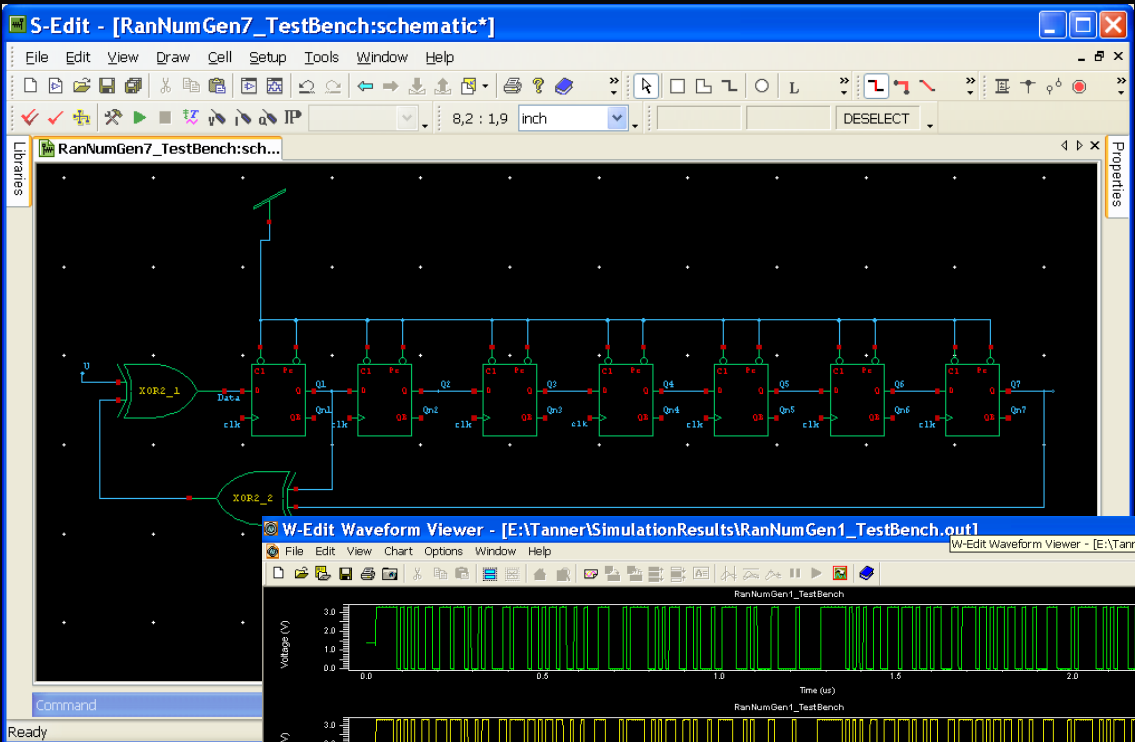


It is Time for Industry...



Tanner





DESIGNLINES | AUTOMOTIVE DESIGNLINE

EDA software Designs Camera ICs on Mars Rovers

By EETimes 03.15.2004 0

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Integrated circuits (ICs) designed using software from Tanner EDA are ensuring the successful operation of the cameras on the NASA Mars Exploration Rovers Opportunity and Spirit. Tanner is a leading developer of EDA (electronic design automation) software for integrated circuit designers.

Scientists and designers at NASA's Jet Propulsion Laboratory (JPL) in Pasadena, California, used L-Edit Pro, Tanner's layout and verification software and T-Spice Pro, Tanner's design entry and simulation software, to design a 1024×1024 CCD (charge coupled device). This effectively shutters, or 'grabs' the images and reads them out to the camera electronics. The CCD design is in use in each of Opportunity and Spirit's different camera systems, which are producing the highest-resolution images ever taken of another planet.





Atlantic Ocean

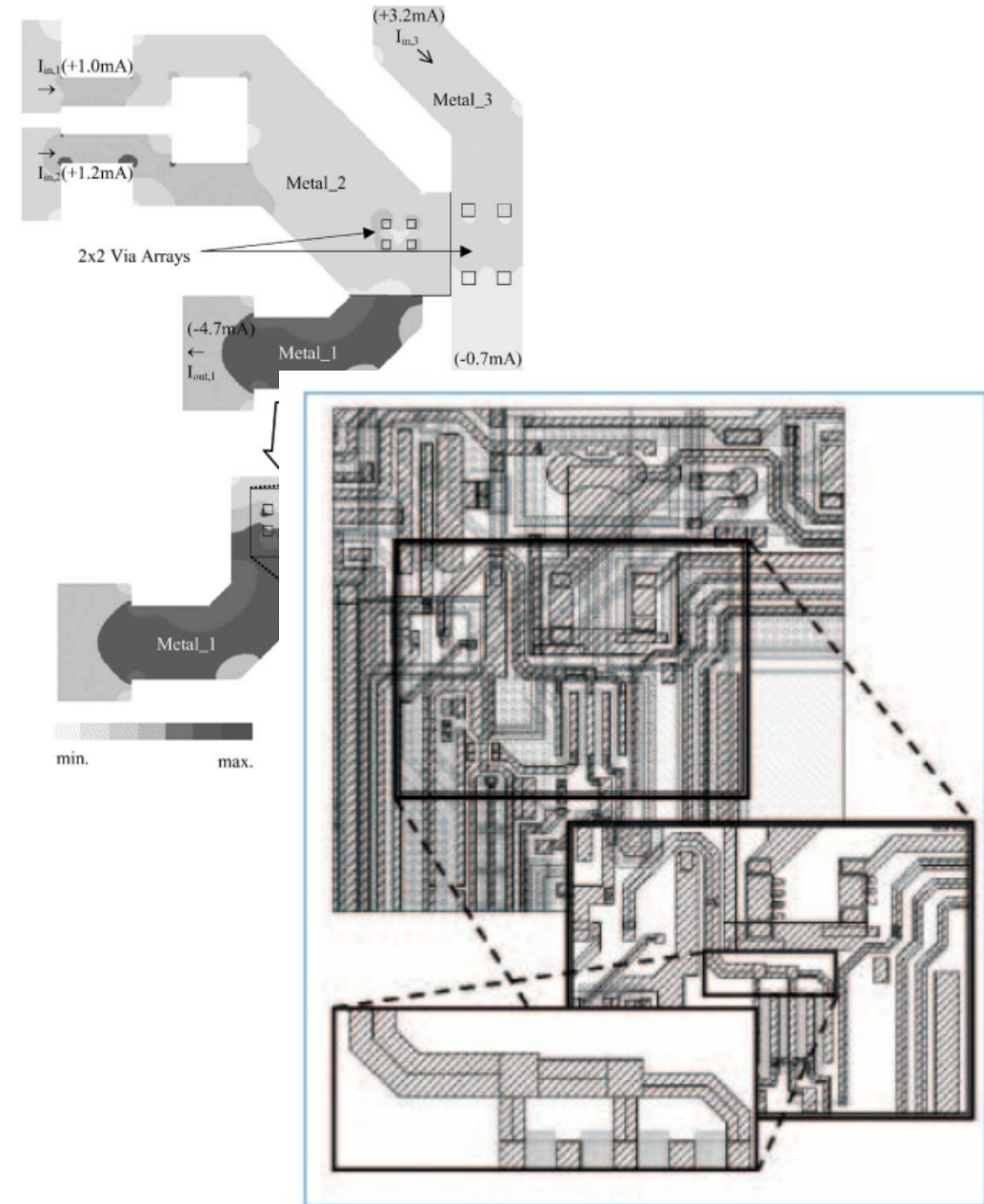
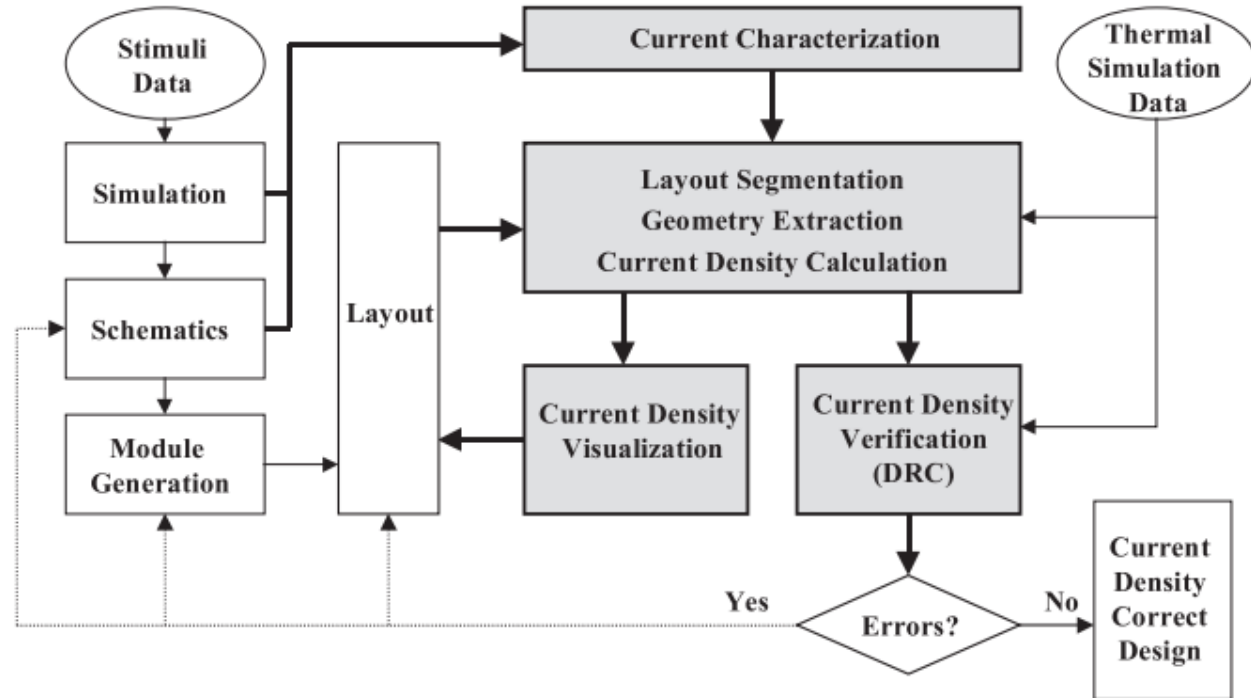
Pacific Ocean

Indian Ocean



Hierarchical Current-Density Verification in Arbitrarily Shaped Metallization Patterns of Analog Circuits

Göran Jerke, *Student Member, IEEE*, and Jens Lienig, *Member, IEEE*







Dresden University of Technology Institute of Electromechanical and Electronic Design

- Professor of Electromechanical and Electronic Design



Dresden University of Technology

Institute of Electromechanical and Electronic Design

- Professor of Electromechanical and Electronic Design
- Director of the Institute
- Five main research areas

Electronic
Design
Automation

Design
of Electronic
Systems

Electro-
mechanical
Systems

Simulation
and
Optimization

Medical Device
Engineering

Overview

From Academia to Industry and Back

Academia: Evolutionary algorithms – the quest for applicability

Industry: From software development to EDA tool management

Academia: Electromigration avoidance and (many) other topics



Overview

From Academia to Industry and Back

Academia: Evolutionary algorithms – the quest for applicability

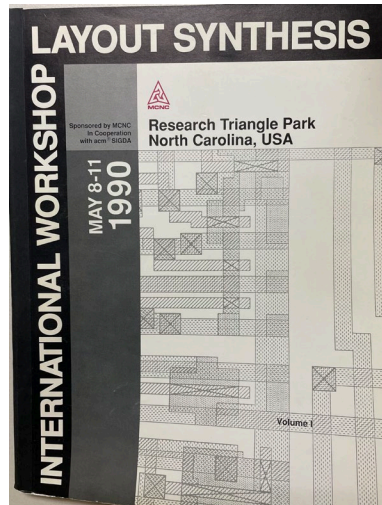
Industry: From software development to EDA tool management

Academia: Electromigration avoidance and (many) other topics

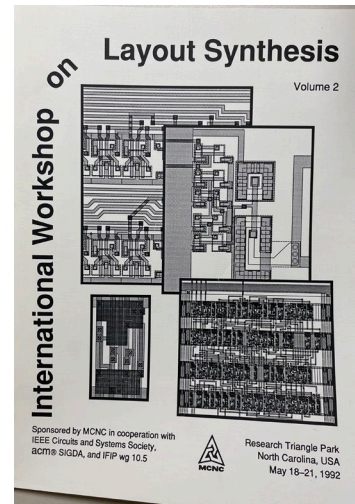
ISPD – More Than an Annual Symposium

International Symposium on Physical Design (ISPD) Predecessors

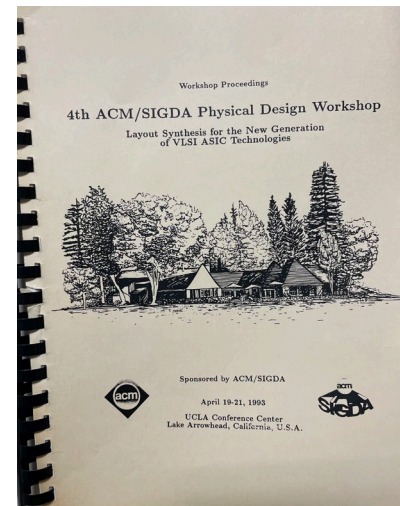
- ACM SIGDA Physical Design Workshop: 1987, 1989, 1991, 1993, 1996
- MCNC Layout Synthesis Workshop: 1988, 1990, 1992



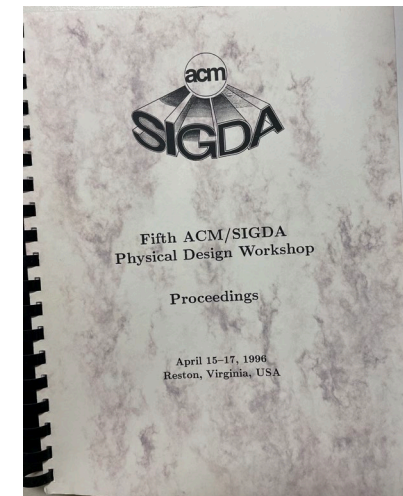
1990



1992

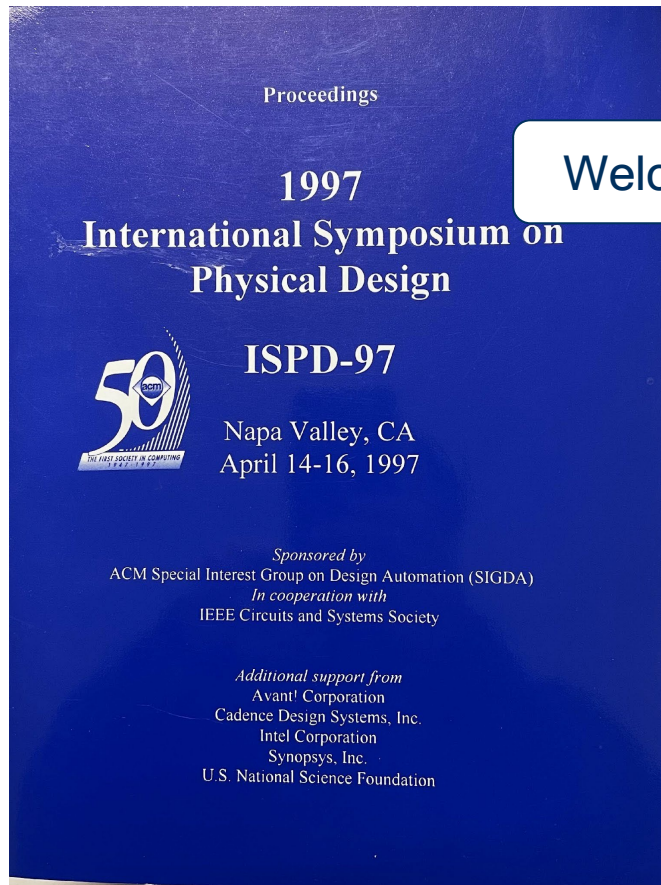


1993



1996

International Symposium First ISPD 1997



Foreword

Welcome to the first International Symposium on Physical Design. The year 1997 will be remembered as yet another year of rapid change in the design industry. Lithography, design complexity, and design time have all grown faster than predicted. Design nodes are now 0.18-micrometers, and the industry is beginning to reach their limits. The industry has been able to reach their limits because of system-level design and circuit synthesis.

The International Symposium on Physical Design (ISPD) was first held in 1987-1996. Its scope includes all aspects of physical design, from logic-level synthesis, to back-end performance. This year's inaugural Symposium focuses on physical design, as well as the necessary interactions between physical design and synthesis tasks. The 15-member Technical Program Committee has accepted a total of 69 papers for poster presentation. These research papers set forth contexts and visions for the key areas of physical design and design methodology – with an emphasis on physical design. A number of the invited presentations are included in these proceedings. The Symposium concludes with a unique perspective as to the critical R&D needs of the industry. Thanks are due to the ACM Special Interest Group on Design Automation (SIGDA) for sponsoring ISPD-97 in cooperation with the IEEE Circuits and Systems Society. Additional support has also been provided by Avant! Corporation, Synopsys, Inc. and the U.S. National Science Foundation. On behalf of the Organizing and Technical Program Committees, we hope that this Symposium is useful and enjoyable. Again, welcome!

Andrew B. Kahng
General Chair

Organizing Committee

General Chair:	A. B. Kahng (UCLA and Cadence)
Past Chair:	G. Robins (Virginia)
Steering Committee:	J. P. Cohoon (Virginia) S. DasGupta (IBM)

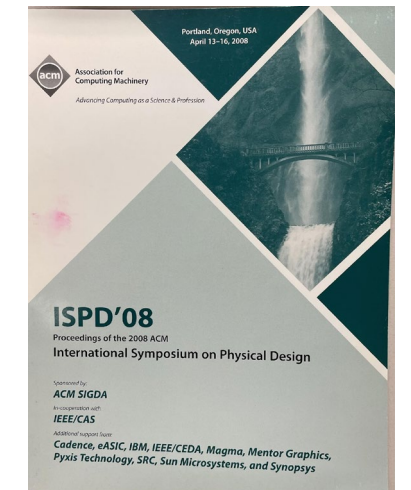
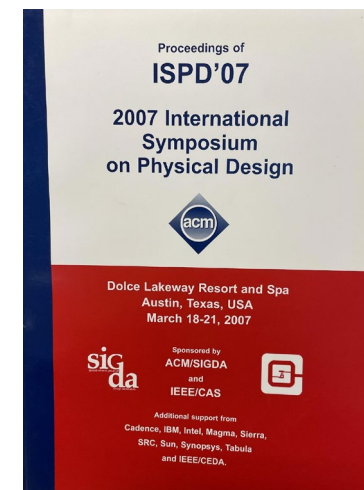
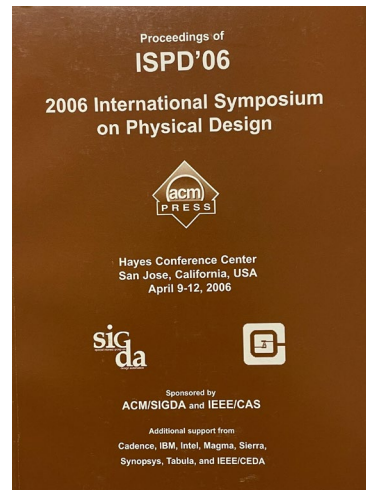
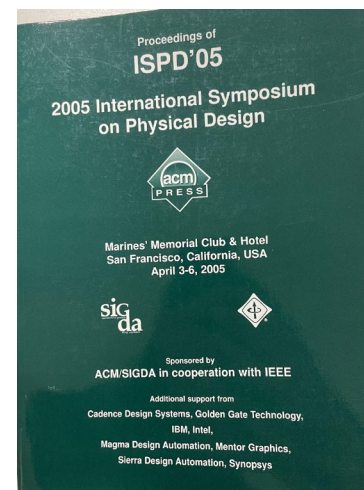
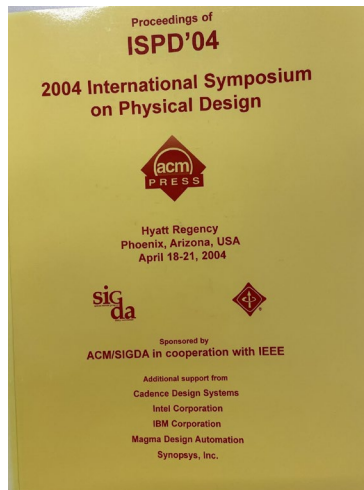
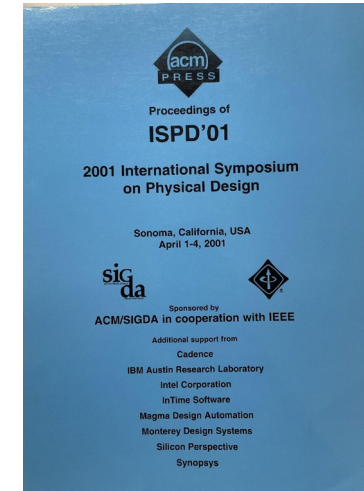
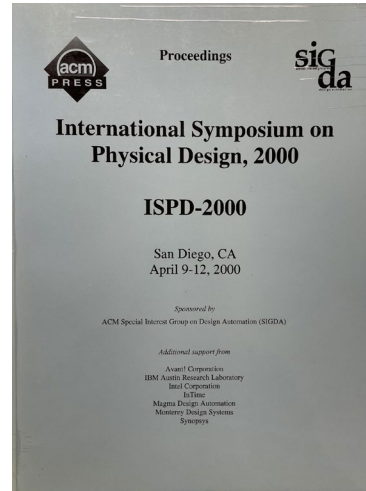
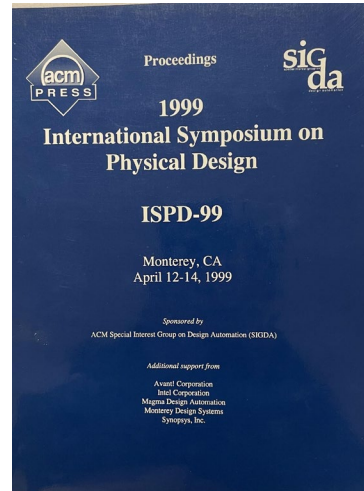
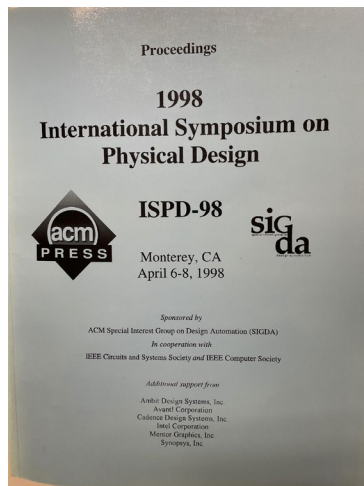
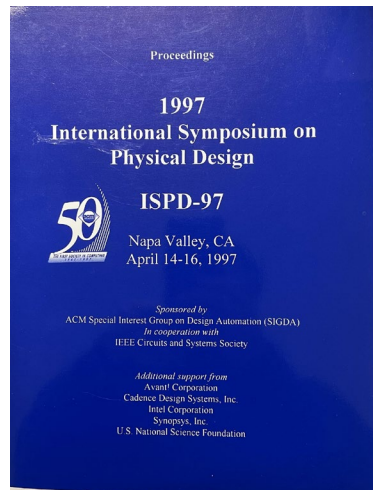
Welcome to the first International Symposium on Physical Design, ISPD-97!

Technical Program Chair:	M. Sarratzaden (Northwestern)
Publicity Chair:	M. J. Alexander (Washington State)
Local Arrangements Chair:	J. Lillis (UCB)
Treasurer:	S. B. Souvannavong

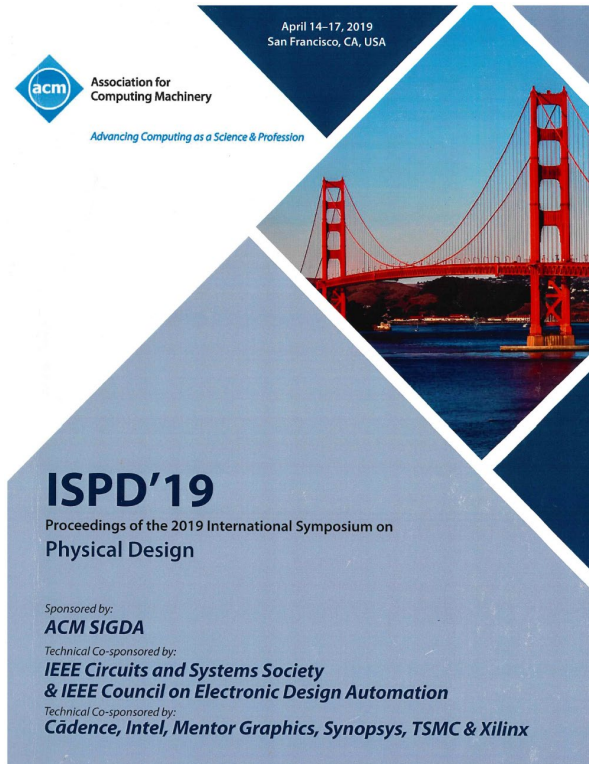
Technical Program Committee

C.-K. Cheng (UCSD)	C. L. Liu (Illinois)
W. W.-M. Dai (UCSC)	M. Marek-Sadowska (UCSB)
J. Frankle (Aristo Technology)	C. Sechen (Washington)
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J. A. G. Jess (Eindhoven)	M. Wiesel (Intel)
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Y.-L. Lin (Tsing Hua)	E. Yoffa (IBM)

International Symposium on Physical Design (ISPD) Annual Symposium 1997 - present



International Symposium on Physical Design Annual Symposium 1997 - present



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ISPD 2019 Organization

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Program Chair: William Swartz (*TimberWolf Systems Inc. & University of Texas at Dallas*)

Past Chair: Chris Chu (*Iowa State University*)

Steering Committee Chair: Chris Chu (*Iowa State University*)

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David Pan (*University of Texas at Austin*)
Prashant Saxena (*Synopsys Inc.*)
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Joseph Shinnerl (*Mentor Graphics, a Siemens Business*)
Ulf Schlichtmann (*Technical University of Munich*)
Vishal Suthar (*Xilinx Inc.*)
Yasuhiro Takashima (*University of Kitakyushu*)
Hua Xiang (*IBM Corp.*)
Gary Yeap (*Synopsys Inc.*)
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Publicity Chair: Laleh Behjat (*University of Calgary*)

Contest Chair: Gracieli Posser (*Cadence Design Systems*)

Webmaster: Erfan Aghaeekiasaraee (*University of Calgary*)

International Symposium on Physical Design (ISPD) ISPD 2020



TPC meeting Nov. 2019
Westminster/Denver, CO

International Symposium on Physical Design (ISPD)

ISPD 2020: **Cancelled by COVID-19**

International Symposium on Physical Design (ISPD) COVID-19: Online ISPD 2021, 2022, 2023



Association for
Computing Machinery

Advancing Computing as a Science & Profession

March 22–24, 2021
Virtual Event, USA



ISPD '21

Proceedings of the 2021 International Symposium on
Physical Design

Sponsored by:

ACM SIGDA

General Chair:

Jens Lienig, Dresden University of Technology, Germany

Steering Committee Chair:

William Swartz, TimberWolf Systems & University of Texas at Dal

Technical Program Chairs:

Laleh Behjat, University of Calgary, Canada & Stephen Yang, USA

Publications Chair:

David Chinnery, Siemens Digital Industries Software, USA



Association for
Computing Machinery

March 27–30, 2022
Virtual Event, Canada



ISPD '22

Proceedings of the 2022 International Symposium on
Physical Design

Sponsor:

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General Co-Chairs:

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Stephen Yang, Leda Technology, USA

Technical Program Chair:

David Chinnery, Siemens Digital Industries Software, USA

Publication Chair:

Iris Hui-Ru Jiang, National Taiwan University, Taiwan



Association for
Computing Machinery

Advancing Computing as a Science & Profession

March 26–29, 2023
Virtual Event, USA



ISPD '23

Proceedings of the 2023 International Symposium on
Physical Design

Sponsored by:

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Technical Sponsors:

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General Chair:

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Steering Committee Chair:

Stephen Yang (Leda Technology, USA)

Technical Program Chair:

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Publication Chair:

Gracieli Posser (Cadence Design Systems, USA)

International Symposium on Physical Design (ISPD) COVID-19: Online ISPD 2021, 2022, 2023




International Symposium on Physical Design (ISPD) Back to normal: 2024, 2025 ...



Association for
Computing Machinery

Advancing Computing as a Science & Profession

March 12-15, 2024
Taipei, Taiwan



ISPD '24

Proceedings of the 2024 International Symposium on
Physical Design

Sponsored by
ACM SIGDA

General Chair:
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Steering Committee Chair:
David Chinnery (Siemens Digital Industries Software)

Technical Program Chair:
Gracieli Posser (Cadence Design Systems)




International Symposium on Physical Design (ISPD) Back to normal: 2024, 2025 ...

March 16–19, 2025
Austin, TX, USA



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ISPD '25

Proceedings of the 2025 International Symposium on
Physical Design

Sponsored by:
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Steering Committee Chair:
Iris Hui-Ru Jiang (National Taiwan University)

Technical Program Chair:
Stephan Held (University of Bonn)

Publication Chair:
Tung-Chieh Chen (Synopsys)



International Symposium on Physical Design (ISPD)

Locations

1997	Napa Valley, CA	2011	Santa Barbara, CA
1998	Monterey, CA	2012	Napa Valley, CA
1999	Monterey, CA	2013	Stateline, NV
2000	San Diego, CA	2014	Petaluma, CA
2001	Sonoma, CA	2015	Monterey, CA
2002	San Diego, CA	2016	Santa Rosa, CA
2003	Monterey, CA	2017	Portland, OR
2004	Phoenix, AZ	2018	Monterey, CA
2005	San Francisco, CA	2019	San Francisco, CA
2006	San Jose, CA	2021	Online
2007	Austin, TX	2022	Online
2008	Portland, OR	2023	Online
2009	San Diego, CA	2024	Taipei, Taiwan
2010	San Francisco, CA	2025	Austin, TX
		2026	Bonn, Germany

ISPD'14: Petaluma, CA



UNITED STATES
DEPARTMENT OF THE INTERIOR
NATIONAL PARK SERVICE

YOSEMITE NATIONAL
PARK


ISPD'16: Hilton, Sonoma, CA



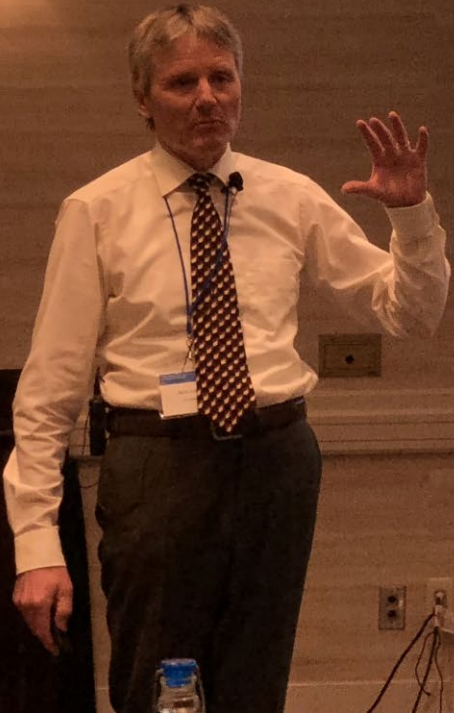
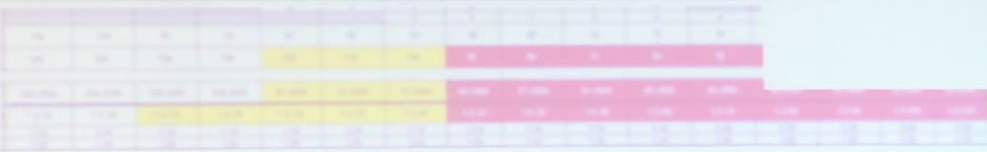
ISPD'18: Monterey, CA



Invited Talks



Year	2018	2020	2022	2024	2026	2028	
Gate length (nm)	12.8	10.65	8.87	7.39	6.16	5.13	↓
On-chip local clock frequency (GHz)	6.69	7.24	7.83	8.47	9.16	9.91	↑
DC equivalent maximum current (μA)	6.92	4.41	2.33	2.98	3.56	4.24	↓ ↑
Metal 1 properties							
Cross-sectional area (nm ²)	302.4	170.1	79.2	79.2	79.2	79.2	↓ →
DC equivalent current densities (MA/cm²)							
Maximum tolerable current density (w/o EM degradation)	1.8	1.1	0.7	0.4	0.3	0.2	↓
Maximum current density (beyond no known solutions)	9.5	5.8	3.5	2.1	1.3	0.8	



Participation statistics

- 12 teams initially participated from Canada, China, France, Germany, Hong Kong, Taiwan, USA
- 7 final placer binary submissions

Rank	Prize
1st	\$2,000
2nd	\$1,000
3rd	\$500

ID	University	Team Lead and Members	Advisor
1	University of Calgary and University of Waterloo	Nima Karimpour Darav, Aysa Fakheri Tabrizi, David Westwick	Lalah Behjat Andrew Kennings
2	Dresden University of Technology	Andreas Krinke, Sergii Osmolovskyi, Johann Kenctel, Matthias Thiele, Steve Bigalke	Jens Lienig
4	Chinese University of Hong Kong	Wing-Kai Chow, Peisahn Tu, Jian Kuang, Zhiqing Liu	Evangeline Young
5	University of Illinois	Chun-Xun Lin, Zigang Xiao, Haitong Tian, Daifeng Guo	Martin Wong
7	National Taiwan University	Chau-Chin Huang, Sheng-Wei Yang, Chin-Hao Chang, Hsin-Ying Lee, Szu-To Chen, Bo-Qiao Lin	Yao-Wen Chang
10	National Chiao Tung University	Ching-Yu Chin	Hung-Ming Chen
11	National Chung Cheng University	Xin-Yuan Su	Mark Po-Hung Lin



International Symposium on Physical Design (ISPD) Contests

2005	Placement	2020	Wafer-Scale DL Accelerator Placement
2006	Placement	2021	Wafer-Scale Physics Modeling Contest
2007	Global Routing	2022	Security Closure of Physical Layouts
2008	Global Routing	2023	Security Closure of Physical Layouts
2009	Clock Network Synthesis	2024	GPU/ML-Enhanced Global Routing
2010	Clock Network Synthesis	2025	Performance-Driven Global Routing
2011	Routability-Driven Placement	2026	Post-Placement Buffering and Sizing
2012	Discrete Gate Sizing Contest		
2013	Discrete Gate Sizing Contest		
2014	Detailed Routing-Driven Placement		
2015	Detailed Routing-Driven Placement		
2016	Routability-Driven FPGA Placement		
2017	Clock-Aware FPGA Placement		
2018	Initial Detailed Routing		
2019	Initial Detailed Routing		

International Symposium on Physical Design (ISPD)
First Lifetime Achievement Award: 2011 Santa Barbara



Prof. Ernest Kuh (1928-2015)
University of California at Santa Barbara

International Symposium on Physical Design (ISPD) Lifetime Achievement Award Recipients

- 2011 Prof. Ernest Kuh
- 2012 Prof. C.-L. Liu
- 2013 Prof. Yoji Kajitani
- 2014 Dr. Bryan Preas
- 2015 Prof. Kurt Antreich
- 2016 Prof. Ralph Otten
- 2017 Prof. Satoshi Goto
- 2018 Prof. Te C. Hu
- 2019 Prof. Alberto Sangiovanni-Vincentelli
- 2021 Dr. Louis K. Scheffer (postponed from ISPD 2020)
- 2022 Prof. Ricardo Augusto Da Luz Reis
- 2023 Prof. Malgorzata Marek-Sadowska
- 2024 Prof. Martin D. F. Wong
- 2025 Prof. Jason Cong

International Symposium on Physical Design (ISPD)
Lifetime Achievement Award Recipients

- 2011 Prof. Ernest Kuh
- 2012 Prof. C.-L. Liu
- 2013 Prof. Yoji Kajitani
- 2014 Dr. Bryan Preas
- 2015 Prof. Kurt Antreich
- 2016 Prof. Ralph Otten
- 2017 Prof. Satoshi Goto
- 2018 Prof. Te C. Hu
- 2019 Prof. Alberto Sangiovanni-Vincentelli
- 2021 Dr. Louis K. Scheffer (postponed from ISPD 2020)
- 2022 Prof. Ricardo Augusto Da Luz Reis
- 2023 Prof. Malgorzata Marek-Sadowska
- 2024 Prof. Martin D. F. Wong
- 2025 Prof. Jason Cong

Thank you very much!